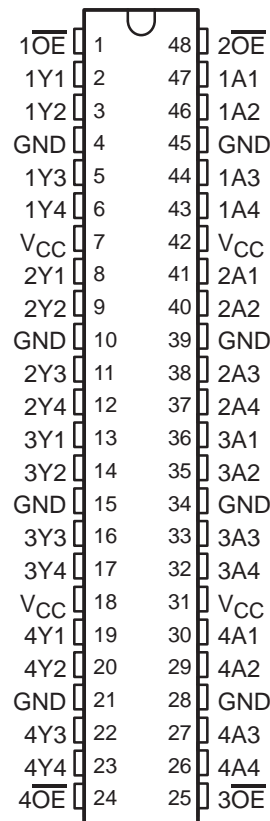


SN54ABTH16244, SN74ABTH16244 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS677D – SEPTEMBER 1996 – REVISED MARCH 2000

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- Typical V_{OLP} (Output Ground Bounce) <1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages

SN54ABTH16244 . . . WD PACKAGE
SN74ABTH16244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABTH16244 devices are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16244 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABTH16244 is characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

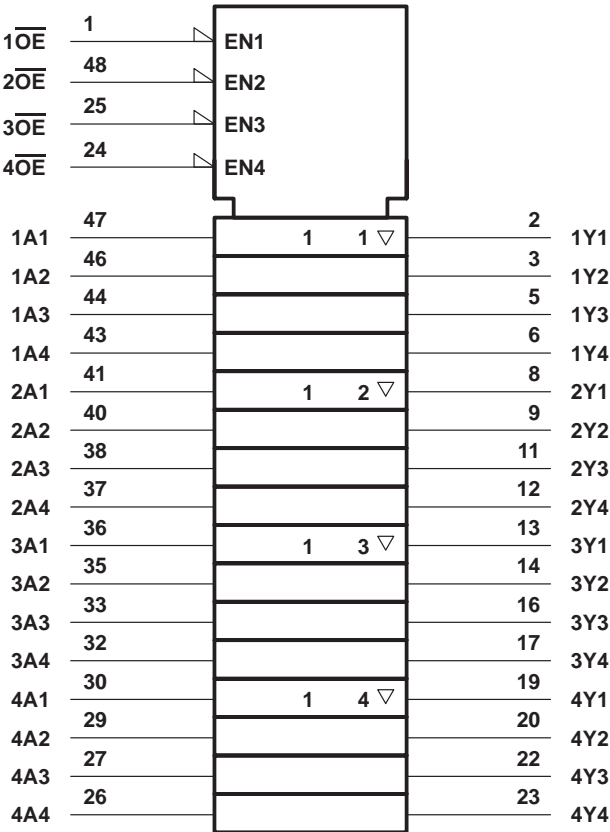
SN54ABTH16244, SN74ABTH16244
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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FUNCTION TABLE
(each buffer)

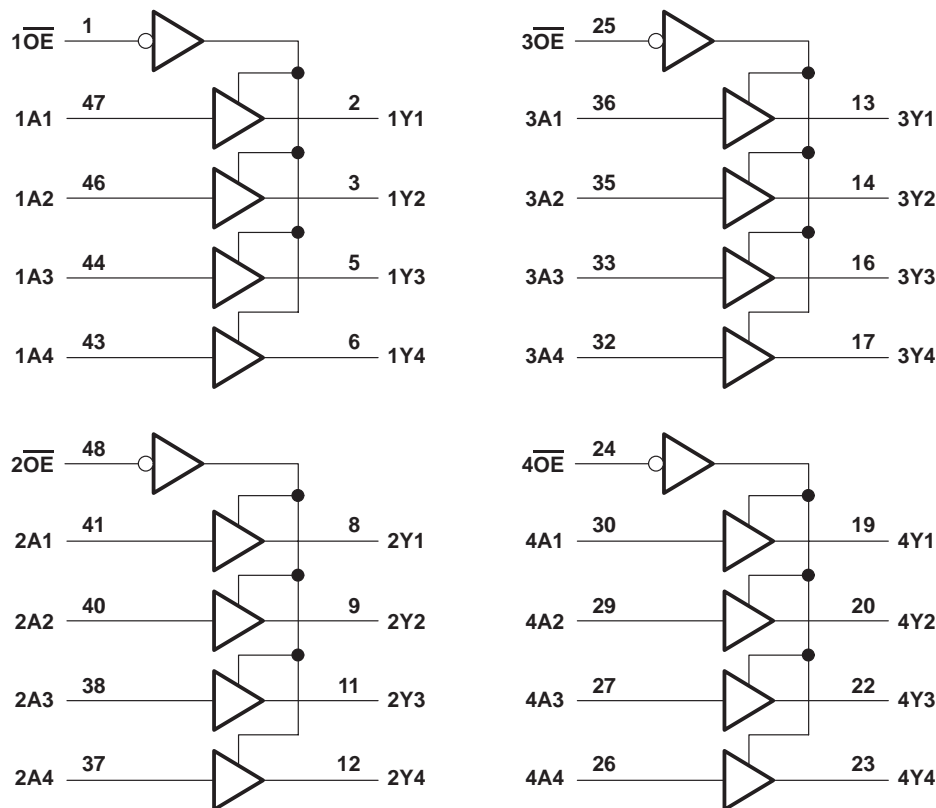
INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	H
L	L	L
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABTH16244	96 mA
SN74ABTH16244	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

SN54ABTH16244, SN74ABTH16244

16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

			SN54ABTH16244		SN74ABTH16244		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		$T_A = 25^\circ\text{C}$			SN54ABTH16244		SN74ABTH16244		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$				–1.2		–1.2		–1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -3\text{ mA}$		2.5			2.5		2.5		V
	$V_{CC} = 5\text{ V}$, $I_{OH} = -3\text{ mA}$		3			3		3		
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -24\text{ mA}$	2			2				
		$I_{OH} = -32\text{ mA}$	2*					2		
V_{OL}	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$			0.55		0.55			V
		$I_{OL} = 64\text{ mA}$			0.55*				0.55	
V_{hys}				100						mV
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = V_{CC}$ or GND				± 1		± 1		± 1	μA
$I_I(\text{hold})$	$V_{CC} = 4.5\text{ V}$	$V_I = 0.8\text{ V}$	100			100		100		μA
		$V_I = 2\text{ V}$	–40			–40		–40		
I_{OZH}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$				10		10		10	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$, $V_O = 0.5\text{ V}$				–10		–10		–10	μA
I_{off}	$V_{CC} = 0$, V_I or $V_O \leq 4.5\text{ V}$				± 100				± 100	μA
I_{CEX}	$V_{CC} = 5.5\text{ V}$, $V_O = 5.5\text{ V}$	Outputs high			50		50		50	μA
I_O^\ddagger	$V_{CC} = 5.5\text{ V}$, $V_O = 2.5\text{ V}$		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs high			3		3		3	mA
		Outputs low			32		32		32	
		Outputs disabled			3		3		3	
ΔI_{CC}^\S	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	$V_I = 2.5\text{ V}$ or 0.5 V			3						pF
C_o	$V_O = 2.5\text{ V}$ or 0.5 V			8						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at $V_{CC} = 5\text{ V}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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SN54ABTH16244, SN74ABTH16244
16-BIT BUFFERS/DRIVERS
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABTH16244		SN74ABTH16244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.3	3.2	0.7	3.6	1	3.5	ns
t_{PHL}			1	2.6	3.7	0.5	4.2	1	4.1	
t_{PZH}	\overline{OE}	Y	1	3	3.8	0.7	4.9	1	4.8	ns
t_{PZL}			1	3.2	4	0.9	5.3	1	4.8	
t_{PHZ}	\overline{OE}	Y	1	3.6	4.4	0.7	5.3	1	4.8	ns
t_{PLZ}			1	2.9	3.7	1	4.6	1	4.1	

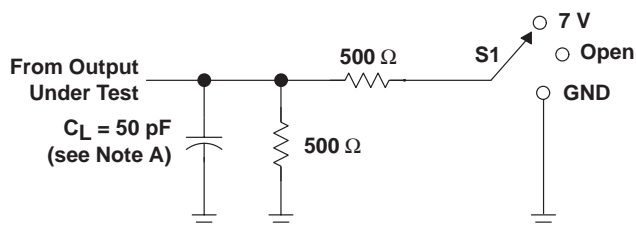
SN54ABTH16244, SN74ABTH16244

16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

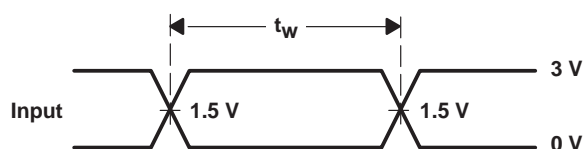
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PARAMETER MEASUREMENT INFORMATION

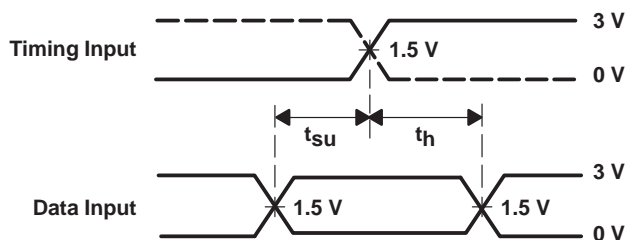


LOAD CIRCUIT

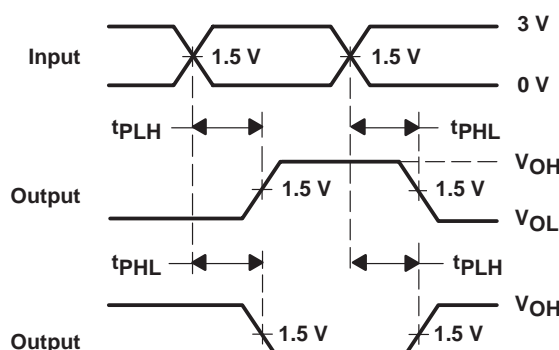
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



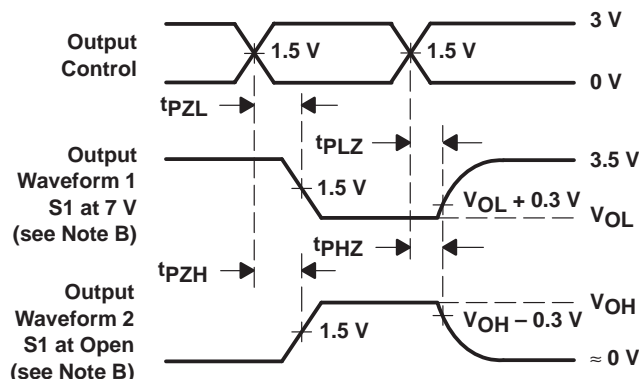
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ABTH16244DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16244
SN74ABTH16244DL	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16244
SN74ABTH16244DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16244

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTH16244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTH16244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

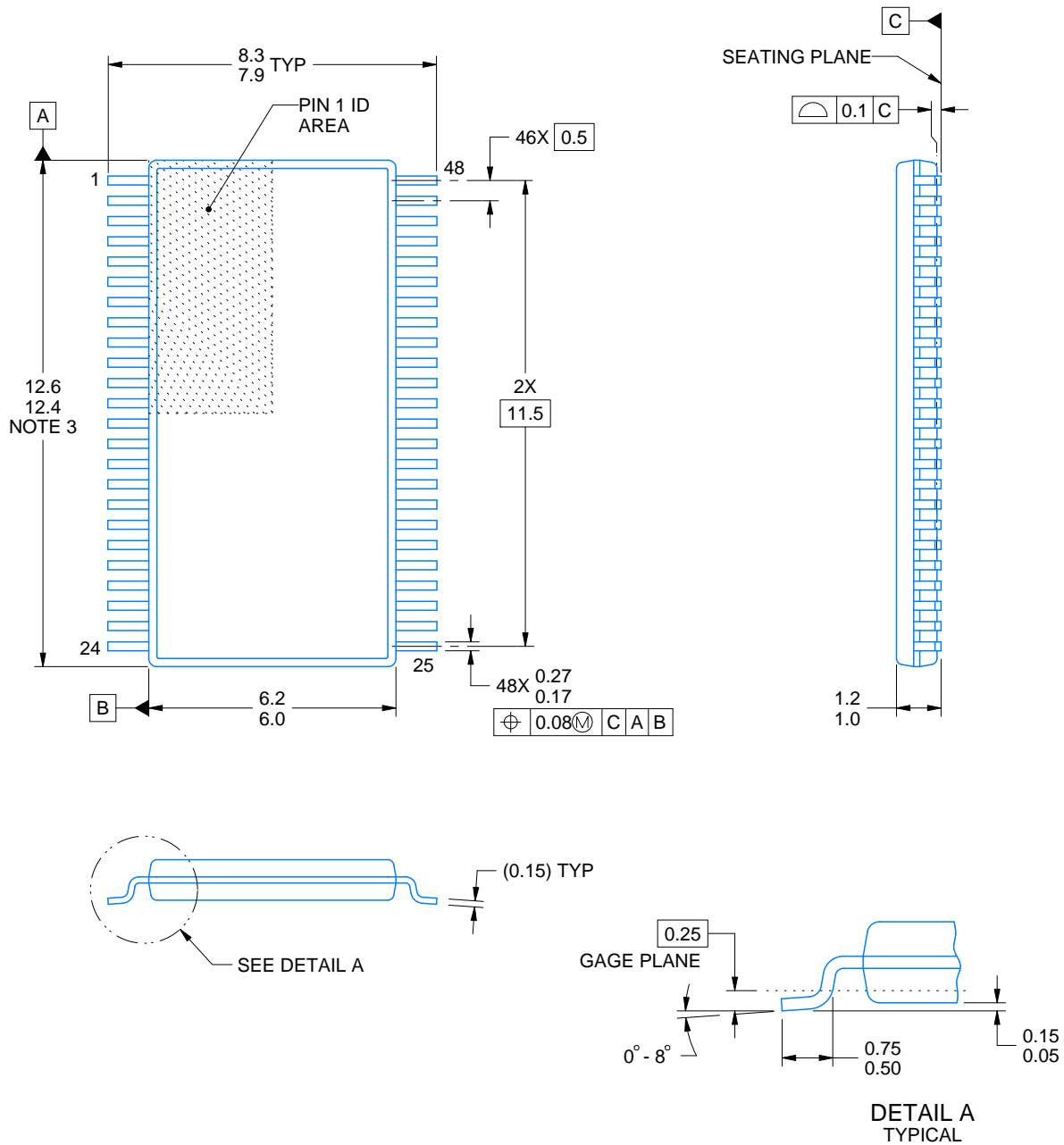
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTH16244DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABTH16244DLR	SSOP	DL	48	1000	367.0	367.0	55.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABTH16244DL	DL	SSOP	48	25	473.7	14.24	5110	7.87



4214859/B 11/2020

NOTES:

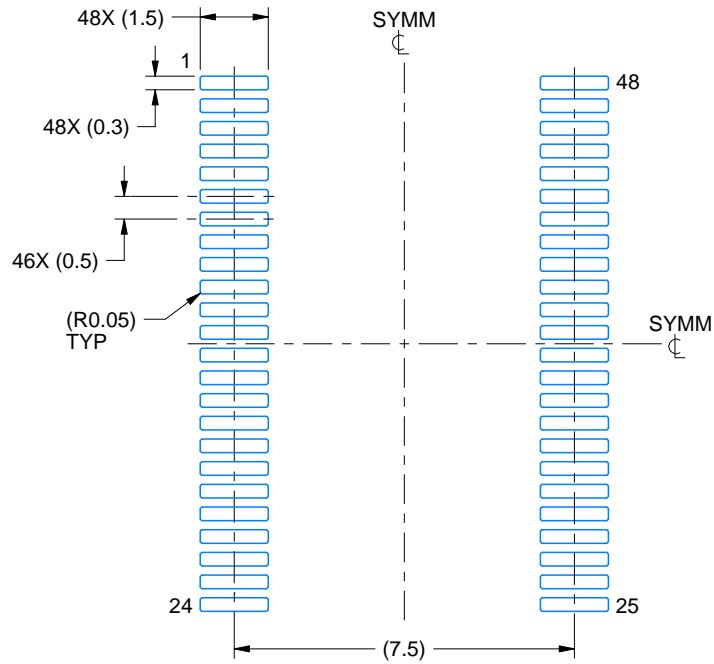
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

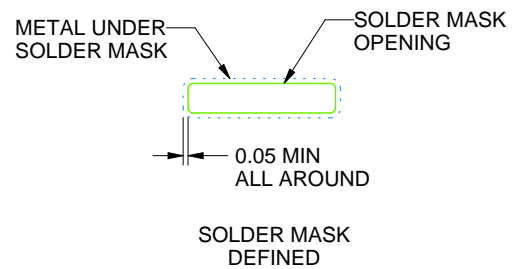
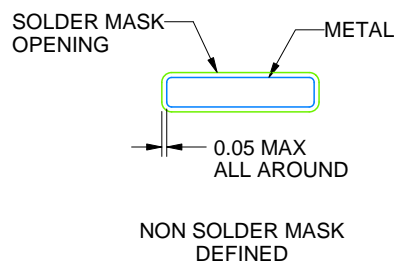
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

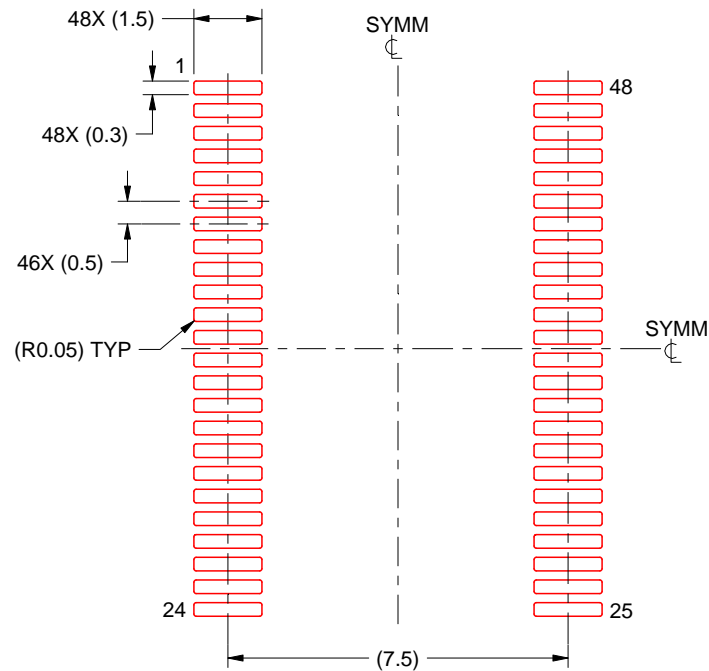
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

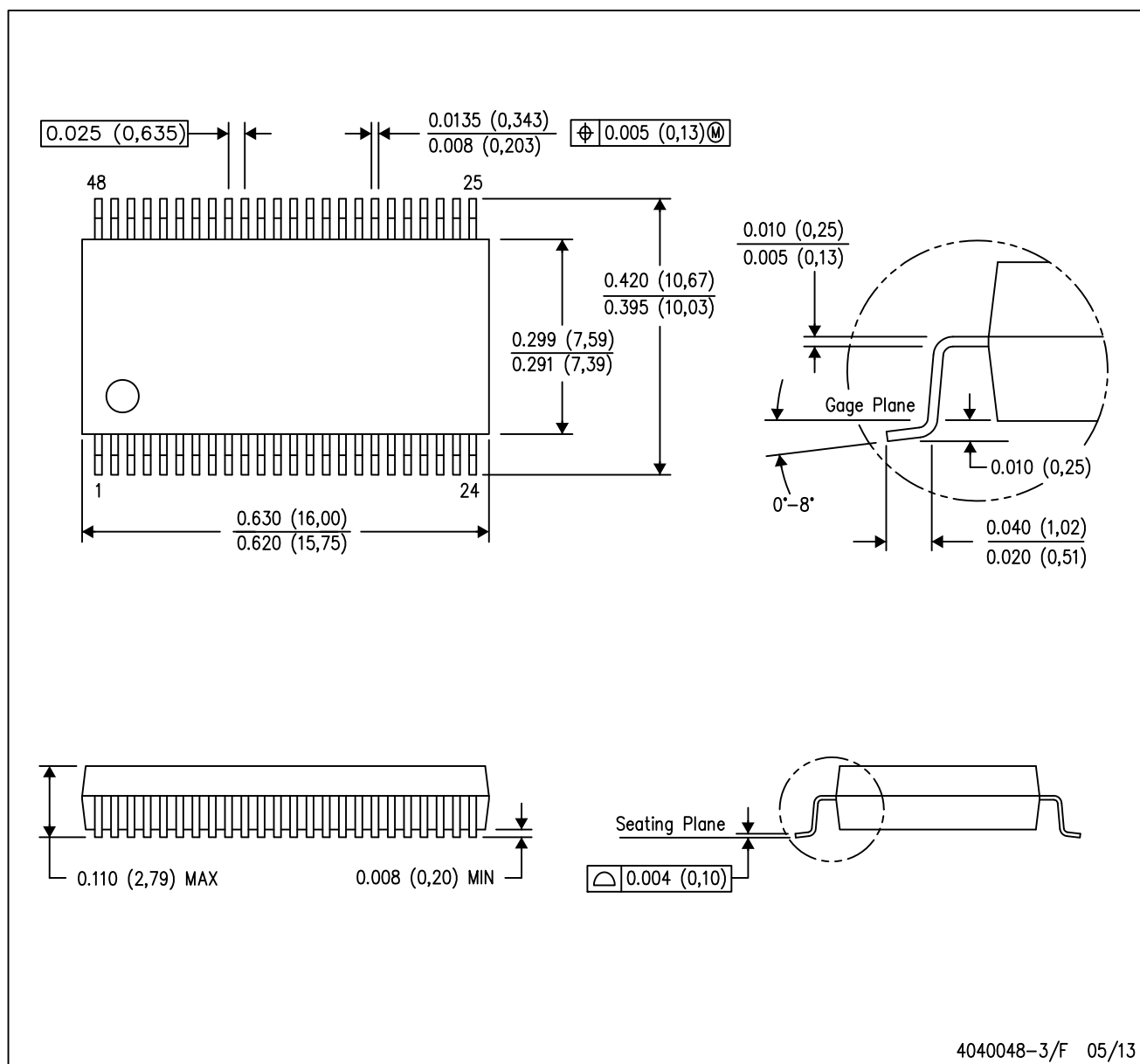
48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

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